## Future Technology Devices International Signs Global Distribution Agreement with Arrow Electronics

**Glasgow, Scotland** – **May 16, 2012** – Future Technology Devices International (FTDI Chip), a leader and innovator specializing in total solutions for converting legacy peripherals to the USB connectivity standard, has signed a global distribution agreement with Arrow Electronics, Inc. Under the agreement, Arrow will distribute FTDI’s complete portfolio to customers in the Americas, EMEA and Asia Pacific regions.

“Arrow brings best-in-class engineering and support infrastructure, successful execution and global reach to the connectivity needs of the USB interface market,” said Fred Dart, founder and chief executive officer of FTDI Chip. “Arrow’s strength in design demand support, global supply chain and value-added services will be appreciated by existing and new FTDI Chip users. With the recent launch of our new X-Chip series of USB bridge interface chips, our teams can now engage the market to deliver the X-treme value proposition of these devices.”

“USB is one of the more ubiquitous standards for data transfer, and FTDI Chip helps simplify USB implementation,” said Jeff Eastman, senior vice president of global supplier marketing and asset management for Arrow Electronics. “The FTDI portfolio offers comprehensive USB solutions for existing and new applications, with full compatibility, support and leadership products. FTDI is a solid addition to our line card and we look forward to a productive relationship.”

**About Future Technology Devices International (FTDI Chip)**

Future Technology Devices International (FTDI Chip) specializes in the design and supply of silicon and software solutions for the Universal Serial Bus (USB). FTDI Chip offers a simple route to USB migration by combining easy-to-implement IC devices with ready-to-use, royalty-free USB firmware and driver software. A wide range of evaluation kits and modules are available to evaluate FTDI Chip’s silicon prior to design-in.

FTDI Chip is a global fab-less semiconductor company with R&D centers in Glasgow and Singapore and regional sales offices in Oregon, USA, Shanghai, China and Taipei, Taiwan. More information is available at: <http://www.ftdichip.com>

Regional sales offices and distributor lists are available <http://www.ftdichip.com/FTSalesNetwork.htm>

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